

Series: Ceramic Chip Antenna

TECHNICAL DATA SHEET

Description: 1.575 GHz GNSS Ceramic

Chip Antenna

PART NUMBER: W3011A

Features:

- Frequency 1559-1606.6MHz
- Gain 1.3 / 2.0 / 2.2dBi
- Size 3.2 x 1.6 x 1.1 mm
- PCB Keep out 4 x 6.25 mm
- Polarization Linear
- · Radiation pattern Omni

Applications:

- L1 GNSS Receivers
- Beidou, GPS, Galileo Glonass
- IoT, M2M
- Asset tracking
- Portable satellite receivers

All dimensions are in mm / inches

Issue: 2019

In the effort to improve our products, we reserve the right to make changes judged to be necessary. CONFIDENTIAL AND PROPRIETARY INFORMATION

This document contains confidential and proprietary information of Pulse Electronics, Inc. (Pulse) and is protected by copyright, trade secret and other state and federal laws. Its receipt or possession does not convey any rights to reproduce, disclose its contents, or to manufacture, use or sell anything it may describe. Reproduction, disclosure or use without specific written authorization of Pulse is strictly forbidden. For more information:

Pulse Worldwide Headquarters 15255 Innovation Drive #100 San Diego, CA 92128 USA Tel:1-858-674-8100 Pulse/Larsen Antennas 18110 SE 34th St Bldg 2 Suite 250 Vancouver, WA 98683 USA Tel: 1-360-944-7551 Europe Headquarters Pulse GmbH & Do, KG Zeppelinstrasse 15 Herrenberg, Germany Tel: 49 7032 7806 0 Pulse (Suzhou) Wireless Products Co, Inc. 99 Huo Ju Road(#29 Bldg,4th Phase Suzhou New District Jiangsu Province, Suzhou 215009 PR China Tel: 86 512 6807 9998



Description: 1.575 GHz GNSS Ceramic

Chip Antenna

PART NUMBER: W3011A

Series: Ceramic Chip Antenna

ELECTRICAL SPECIFICATIONS

Antenna Type Chip antenna

Frequency 1559-1563MHz

1574.4-1576.4MHz 1598.6-1606.6MHz

Nominal Impedance 50Ω

Return Loss (Max) -7 / -10 / -10 dB

Radiation Pattern Omni

Gain(Min) 1.3 / 2.0 / 2.2dBi

Efficiency(Min) 65 / 75 / 78 %

Polarization Vertical

Power Withstanding 2W

MECHANICAL SPECIFICATIONS

Compact size 3.2 x 1.6 x 1.1mm

Weight 0.033g
Fixing system SMT

MSL(MOISTURE SENSITIVITY LEVEL) 1

ENVIRONMENTAL SPECIFICATIONS

Operating Temperature $-40 \sim +85^{\circ}$ C Storage Temperature $-40 \sim +85^{\circ}$ C

RoHS Compliant Yes



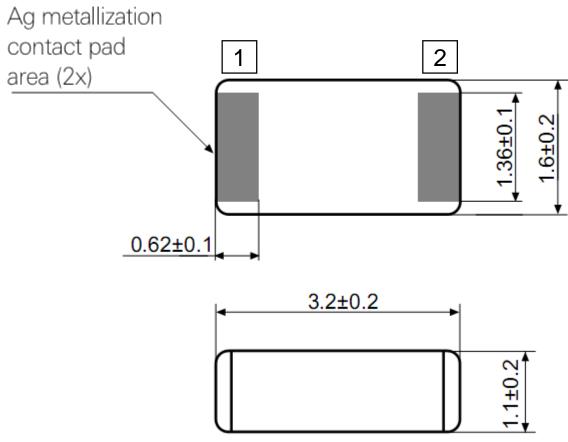
Description: 1.575 GHz GNSS Ceramic

Chip Antenna

PART NUMBER: W3011A

Series: Ceramic Chip Antenna

MECHANICAL DRAWING



Antenna features

No.	Terminal name	Terminal Dimensions
1	Feed / GND	0.62 x 1.36 mm
2	Feed / GND	0.62 x 1.36 mm

Antenna is symmetrical.

Either of terminals 1 or 2 can be feed / GND





Description: 1.575 GHz GNSS Ceramic

Chip Antenna

PART NUMBER: W3011A

Series: Ceramic Chip Antenna

W3011 GPS Antenna PWB Layout

Ground cleared under antenna, clearance area 4.00 x 6.25 mm Matching and tuning component value and placement depend on application and surrounding mechanics / materials.

Feed line should be designed to match 50 Ω characteristic impedance, depending on PWB material and thickness.

Recommended test board layout for electrical characteristic measurement, test board outline size 80 x 37 mm.





Description: 1.575 GHz GNSS Ceramic

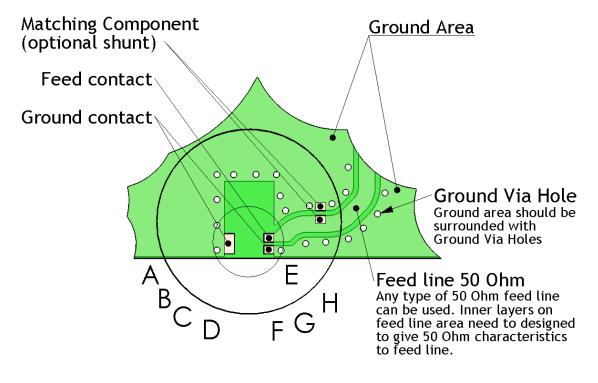
Chip Antenna

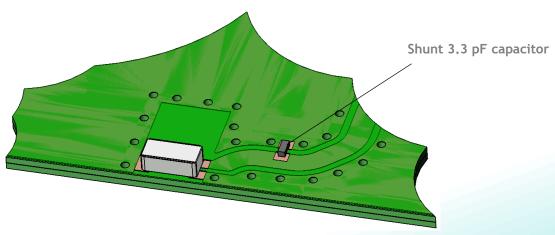
PART NUMBER: W3011A

Series: Ceramic Chip Antenna

PWB layout for W3011A GPS Antenna

Note: All dimensions are in metric system.









Description: 1.575 GHz GNSS Ceramic

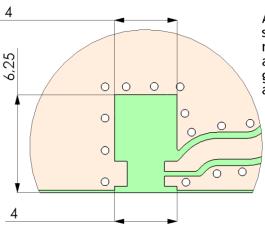
Chip Antenna

PART NUMBER: W3011A

Series: Ceramic Chip Antenna

Ground clearance area for W3011A GPS Antenna

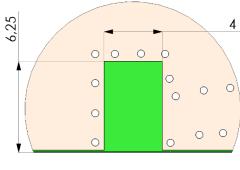
Ground clearance area (4,00 x 6,25 mm)



All metallization should be removed from all PWB layers on ground clearance area (4,00 x 6,25 mm).

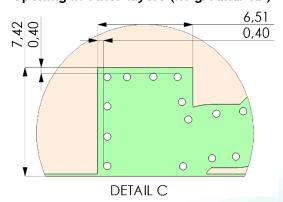
DETAIL A

Opening in bottom/inner ground layers



DETAIL B

Opening in other layers (no ground/RF)





Description: 1.575 GHz GNSS Ceramic

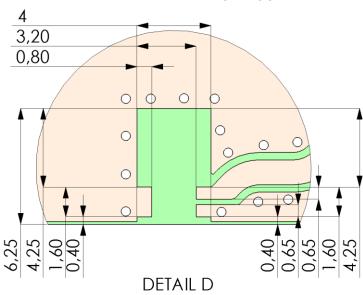
Chip Antenna

PART NUMBER: W3011A

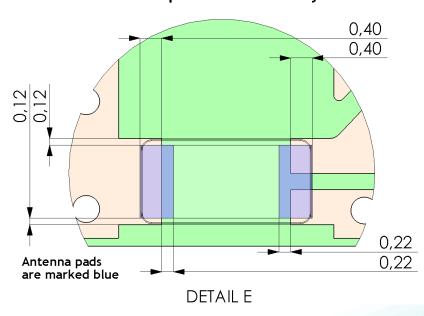
Series: Ceramic Chip Antenna

PWB pad dimensions and antenna position for W3011A GPS Antenna

Pad dimensions in top copper



Antenna position on PWB layout





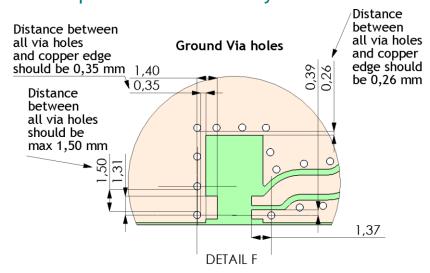
Description: 1.575 GHz GNSS Ceramic

Chip Antenna

PART NUMBER: W3011A

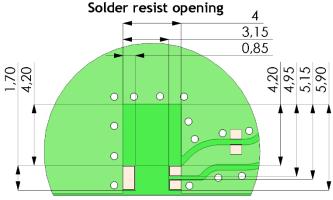
Series: Ceramic Chip Antenna

Typical Ground via hole placement in PWB layout for W3011A GPS Antenna



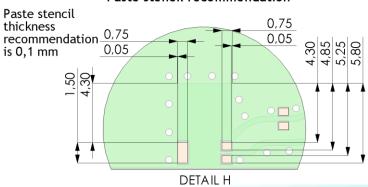
Solder resist opening and paste stencil recommendations for W3011A GPS





DETAIL G

Paste stencil recommendation



Issue: 2019

ROHS



Series: Ceramic Chip Antenna

TECHNICAL DATA SHEET

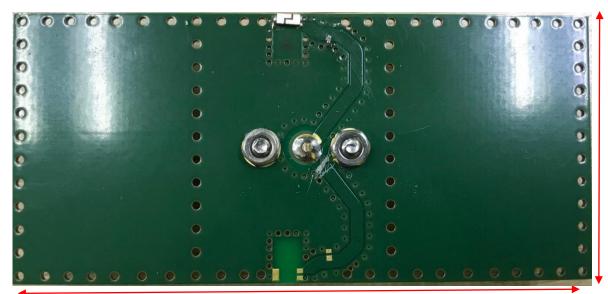
Description: 1.575 GHz GNSS Ceramic

Chip Antenna

PART NUMBER: W3011A

TEST SETUP

All RF parameters tested on 80x37mm sized test board. Antenna position on side center of PCB long edge.



37mm

80mm





Description: 1.575 GHz GNSS Ceramic

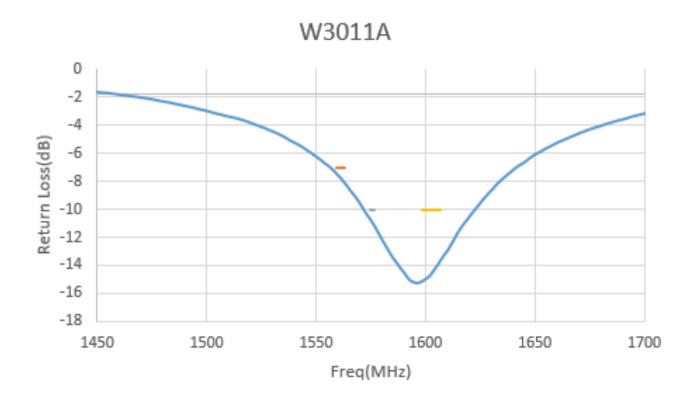
Chip Antenna

PART NUMBER: W3011A

Series: Ceramic Chip Antenna

CHARTS

Return Loss vs Frequency







Description: 1.575 GHz GNSS Ceramic

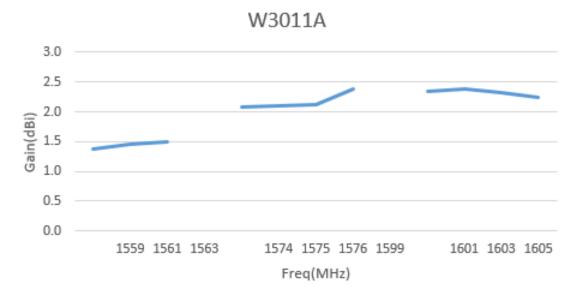
Chip Antenna

PART NUMBER: W3011A

Series: Ceramic Chip Antenna

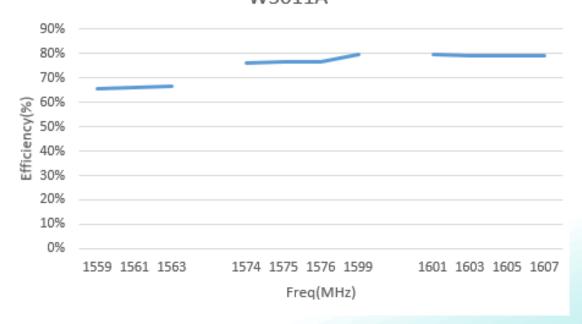
CHARTS

Gain vs Frequency



Radiation Efficiency vs Frequency

W3011A







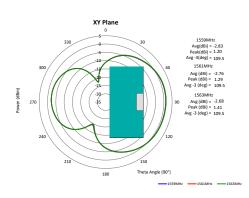
Description: 1.575 GHz GNSS Ceramic

Chip Antenna

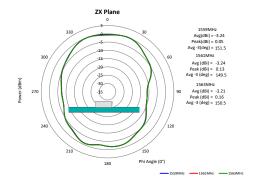
PART NUMBER: W3011A

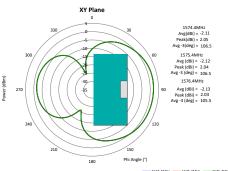
Series: Ceramic Chip Antenna

CHARTS



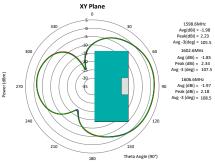
Beidou B1



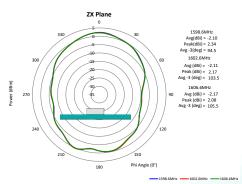


GPS L1





Glonass L1





Description: 1.575 GHz GNSS Ceramic

Chip Antenna

PART NUMBER: W3011A

Series: Ceramic Chip Antenna

Recommendation for reflow soldering process

Printing stencil thickness 0,15 - 0,25 mm is recommended for the solder paste. The maximum soldering temperature should not exceed 260°C. The temperature profile recommendations for reflow soldering process is presented in the Figures 1 and 2. The reflow profile presented in figure 1 describes minimum reflow temperatures. The reflow profile presented in figure 2 describes maximum reflow temperatures. located at the center of the coverage area.

	Method of heat transfer	Controlled hot air convection	
1	Average temperature gradient in preheating	2.5 °C/s	
2	Soak time	2-3 minutes	
3	Max temperature gradient in reflow	3 °C/s	
4	Time above 217 °C	Max 30 sec	
5	Peak temperature in reflow	230 ℃ for 10 seconds	
6	Temperature gradient in cooling	Max -5 °C/s	

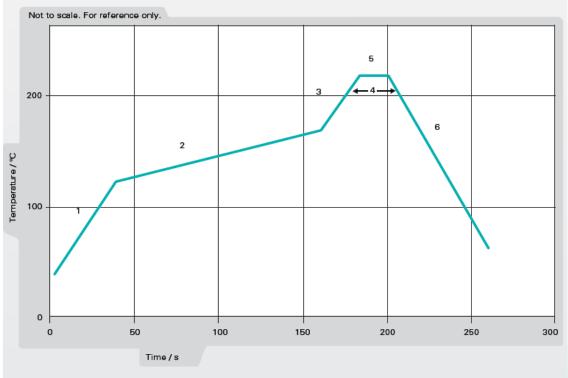


Figure 1. Minimum temperature profile recommendation for reflow soldering process

13



Description: 1.575 GHz GNSS Ceramic

Chip Antenna

PART NUMBER: W3011A

Series: Ceramic Chip Antenna

Recommendation for reflow soldering process

	Method of heat transfer	Controlled hot air convection
1	Average temperature gradient in preheating	2.5 °C/s
2	Soak time	2-3 minutes
3	Max temperature gradient in reflow	3 °C/s
4	Time above 217 °C	Max 60 sec
5	Time above 230 °C	Max 50 sec
6	Time above 250 °C	Max 10 sec
7	Peak temperature in reflow	260 °C for 5 seconds
8	Temperature gradient in cooling	Max -5 °C/s

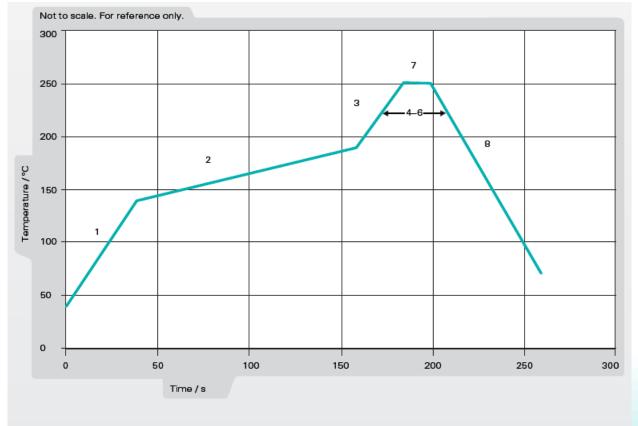


Figure 2. Maximum temperature profile recommendation for reflow soldering process



Description: 1.575 GHz GNSS Ceramic

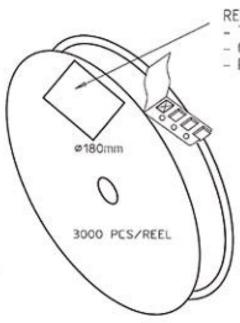
Chip Antenna

PART NUMBER: W3011A

Series: Ceramic Chip Antenna

PACKAGING

Taping package 3000PCS/Reel 30000PCS/Carton box



REEL LABEL INFORMATION:

- TRACEABILITY
- QUANTITY
- PRODUCT CODE

CARRIER TAPE H85-00125 width=8,00 depth=1,22 COVER TAPE H85-00126 width=5,60

LENGTH OF TAPE:

- Leader section: 50 empty cavities before component section
- Trailer section: 25 empty cavities after component section.

Empty part cavities at leader and trailer section of the tape must be sealed with top cover tape.

BOX H85-00128 (182x182x132) 1 pcs

- LABEL

1 pcs/BOX

REEL H85-00127

10 pcs

(D180, W12)

- REEL LABEL

1 pcs/REEL



Description: 1.575 GHz GNSS Ceramic

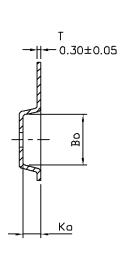
Chip Antenna

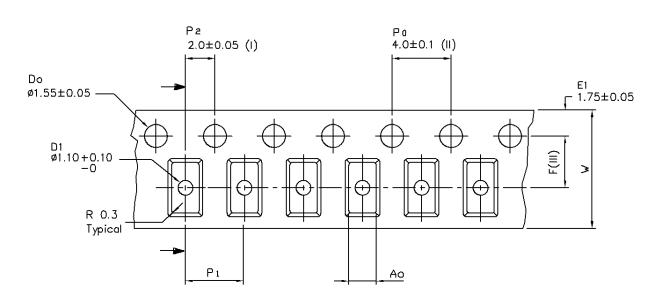
PART NUMBER: W3011A

Series: Ceramic Chip Antenna

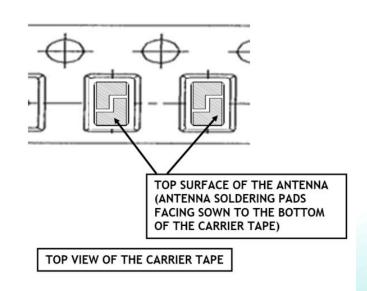
PACKAGING

Tape size





Ao	1.85	+/- 0.1
Во	3.43	+/- 0.1
Ко	1.22	+/- 0.1
F	3.50	+/- 0.05
P ₁	4.00	+/- 0.1
W	8.00	+/- 0.1



Mouser Electronics

Authorized Distributor

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

Pulse: W3011A